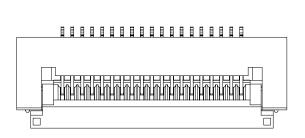
# **Product Specification**

1ssued Date 99.04.16



FPC Connector 0.5 Pitch R/A ZIF SMT TYPE

Update List:						
Item Update Description Rev. Issued Date Revisor						
1	New Edit	Α	99.04.16			

## **Product Specification**

Issued Date 99.04.16

### 1. SCOPE

#### 1.1. Contents

This specification covers the performance, tests and quality requirements for the (With Cover), R/A,SMT, 0.5 mm Pitch, 1.50 mm H, Connector.

#### 1.2. Qualification

When tests are performed on the subject product line, the procedures specified in FPC 0.5mm Pitch series specifications shall be used. All inspections shall be performed using the applicable inspection plan and product drawing.

## 2. ORDERING INFORMATION

PART NO.: FPC 05 15 01 XX L X
1 2 3 4 5 6 7

1	Series name	FPC Connector
2	Pitch	0.5 mm
3	High	1.5mm
4	Mode	01:Clamshell FFC T=0.3mm / 02:Drawer FFC T=0.3mm 03:Clamshell FFC T=0.2mm / 04:Drawer FFC T=0.2mm
5	Number of terminals	04-68PIN
6	Assembly style	L:Low Contact SMT Type / U:Upper Contact SMT Type D:Double-Face Contact SMT Type
7	Plating	G:Gold flash over Nickel / T:Tin OVER Nickel

### 3. CONNECTOR DIMENSIONS

See attached drawings.

### 4. MATERIAL

Housing:	Hight-Temp plastic Color : White			
	Flammability Rating (UL94V-0)			
Actuator	Hight-Temp plastic Color : Black.			
	Flammability Rating (UL94V-0)			
Contact :	Copper alloy			
Peg:	Copper alloy			
Contact Plating	See Ordering Information			
Peg Plating:	Tin over Nickel			

## 5. ACCOMMODATED P.C.B. LAYOUT

See attached drawings.



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## 6. RATING.

ITEM	STANDARD				
Operating Voltage (Max.)	25 V AC/DC				
Current Rating (Max.)	0.3 A AC/DC				
Operating Temperature	-25°C ~ +85°C (Including terminal temperature rise)				

### 7. PERFORMANCE

	TEST ITEM	REQUIREMENT	PROCEDURE					
1	Examination of Product	Meets requirements of product drawing. No physical damage.	Visual inspection.					
	ELECTRICAL REQUIREMENT							
2	Contact Resistance	[ 30 ] m Ohm Max(Initial)	Subject mated contacts assembled in housing to 20mV Max open circuit at 10mA Max. Refer to Fig.3					
	Dielectric withstanding Voltage	No creeping discharge or flashover shall occur. Current leakage: 0.5 mA MAX	[ 500 ]VAC for 1minute Test between adjacent circuits of unmated connector.					
4	Insulation Resistance	[ 500 ] M Ohm Min.(Initial)	Impressed voltage 500 VDC. Test between adjacent circuits of unmated connector.					
5	Temperature Rising	30°C Max. Under loaded rating current	Contact series-wired, apply test current of loaded rating current to the circuit, and measure the temperature rising by probing on soldered areas of contacts, after the temperature becomes stabilized deduct ambient temperature from the measured value.					
		MECHANICAL REQUIRE	MENT					
6	Contact / Peg Retention Force	0.100 kgf Min.	Apply axial pull out force at the rate of [ 25.4±3 ] mm/min on the terminal assembled in the housing.					
_ /	FPC/FFC Retention Force	0.030 kgf/Pin Min.(PIN>=17) 0.500 kgf/ Min. (PIN<17)	Operation Speed : [ 25.4±3 ] mm/min Measure the force required to unmate connector.					
8	Durability	Contact Resistance: [ 50 ] m Ohm Max(Final)	Operation Speed: [ 10 ] cycle-max./min Durability Cycles: 50 Cycles					
9	Vibration	No electrical discontinuity greater than 0.1 or 1 $\mu$ sec shall occur. See Note.	Subject mated connectors to 10-55-10 Hz traversed in 1minutes at 1.52mm amplitude 2 Hours each of 3 mutually perpendicular planes. 100mA Max. Applied.					
10	Mechanical Shock	No electrical discontinuity greater than 0.1 or 1 $\mu$ sec shall occur. See Note.	Accelerate Velocity: 490m/s2 (50G) Waveform: Half-sine shock plus Duration: 11msec No. of Drops: 3 drops each to normal and reversed directions of X, Y and Z axes, totally 18 drops, passing DC 100mA max. Current during the test.					

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	TEST ITEM	REQUIREMENT	PROCEDURE					
MECHANICAL REQUIREMENT								
11	Solder ability	The inspected area of each lead must have 95% solder coverage minimum.						
		ENVIRONMENTAL REQUIRE	MENTS					
12	Resistance to Reflow Soldering Heat	No physical damage shall occur. (Lead-Free)	Pre Heat : 150~180 °C , 90 ± 30sec. Heat : 230 °C Min., 30±10sec. Peak Temp. : 260+0/-5 °C , 10sec. or less Duration : 3 cycles Refer to Fig.4					
13	Thermal Shock	Contact Resistance: [ 50 ] m Ohm Max(Final)	Mated Connector -55+/-3°C (30 min.), +85+/-2°C (30 min) Perform this a cycle, repeat 5 cycles					
14	Humidity-Temperature Contact Resistance: [ 50 ] m Ohm Max(Final)		Mated Connector 25~65°C, 90~95% RH, 10 Cycles					
15	Temperature Life (Heat Aging) Contact Resistance: [ 50 ] m Ohm Max(Final)		Mated Connector 85°C, 250 hours,					
16	Salt Spray	No detrimental corrosion allowed in contact area and base metal exposed. Contact Resistance: [ 40 ] m Ohm Max(Final)	Subject mated connectors to 35+/-2°C and 5+/-1% salt condition for 48hours. After test, rinse the sample with water and recondition the room temperature for 1 hour. EIA-364-26B, Condition B					

Figure 1 (End)

NOTE: Shall meet visual requirements, show no physical damage, and meet requirement of additional tests as specified in the test sequence in Figures 2

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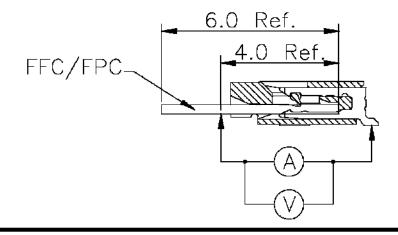
## 7.1. PRODUCT QUALIFICATION AND REQUALIFICATION TEST

	Test Group									
Test or Examination		В	С	D	E	F	G	Н	I	J
		Test Sequence (a)								
Examination of Product	1, 7	1, 9	1, 6	1, 5	1, 5	1, 5	1, 5	1, 3	1, 3	1, 3
Contact Resistance		2, 8	2, 5	2, 4	2, 4	2, 4	2, 4			
Dielectric withstanding Voltage	3, 6									
Insulation Resistance	2, 5									
Temperature Rising								2		
Contact/ Peg Retention Force		3, 7								
FPC/FFC Retention Force		4, 6								
Durability		5								
Vibration			3							
Mechanical Shock			4							
Solder ability										2
Resistance to Soldering Heat									2	
Thermal Shock				3						
Humidity Temperature Cycling	4				3					
Temperature Life						3				
Salt Spray							3			

Figure 2

- NOTE (a) Numbers indicate sequence in which tests are performed.
  - (b) Discontinuities shall not take place in this test group, during tests. Figure 3.

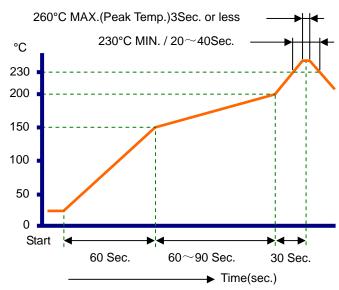
### **Contact Resistance**



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## 8. INFRARED REFLOW CONDITION



NOTE: Please check the re-flow soldering condition by your own devices beforehand . Because the condition changes by the soldering devices, p.c. boards, and so on.

### 9. TAPE AND REEL PACKAGE SPECIFICATION

9-1. Tape and Reel Dimensions: See attached drawings.

### 9-2. Specification

No. of Contacts	Width	? Pcs / Reel	? Reels / Carton
04~08	16	4 K / 1	14 / 1
09~24	24	4 K / 1	10 / 1
25~36	32	4 K / 1	8 / 1
37~40	44	4 K / 1	6 / 1

Export Carton Layer: 3 Layers Carton Size: 350x350x300mm

